



SOT371-1

plastic shrink small outline package; 56 leads; body width 7.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP56
Package type industry code	SSOP56
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-118
Mounting method type	S (surface mount)
Issue date	18-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		18.3	-	18.45	18.55	mm
E	package width		7.4	-	7.5	7.6	mm
A	seated height		[tbd]	-	2.8	2.8	mm
A ₂	package height		2.2	-	2.3	2.35	mm
n ₂	actual quantity of termination		-	-	56	-	

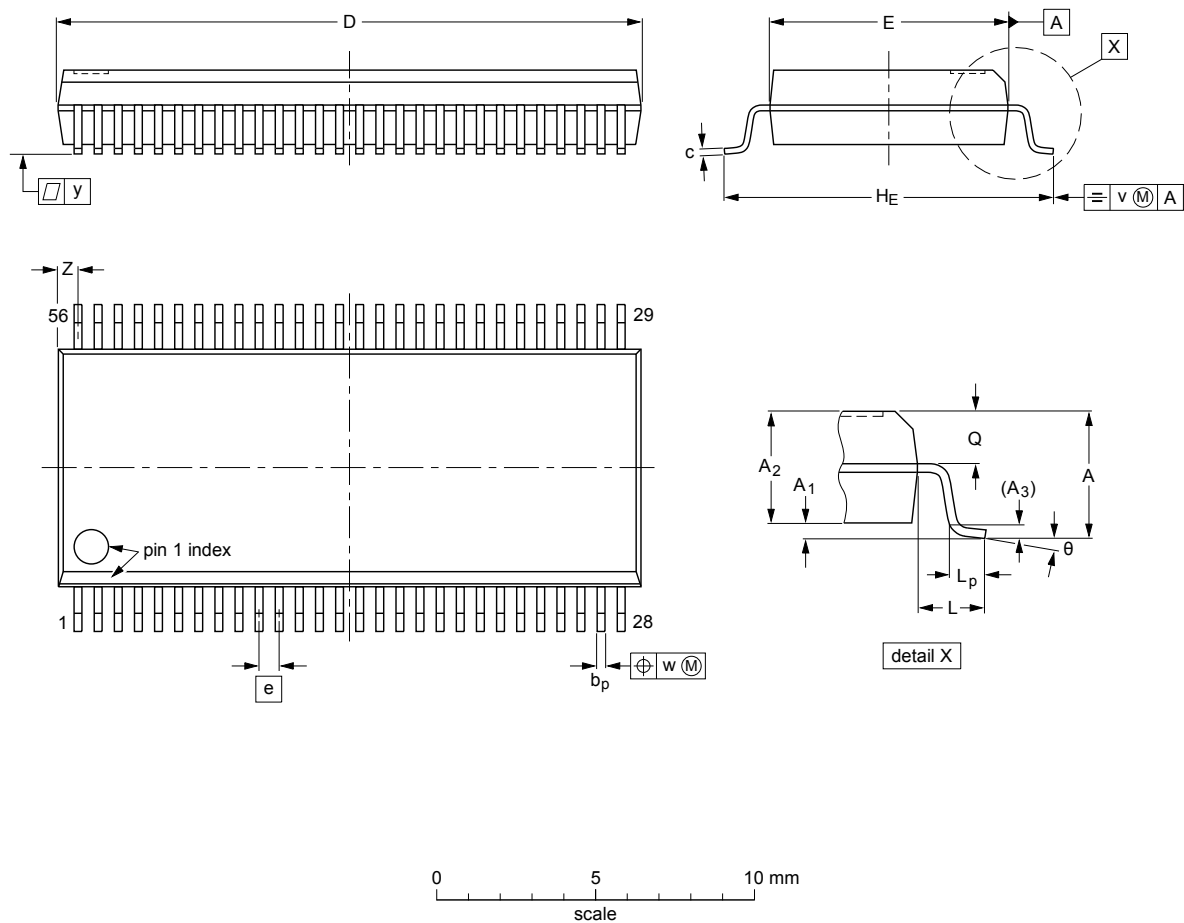


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2. Package outline

SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

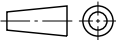
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT371-1		MO-118				99-12-27 03-02-18

Fig. 1. Package outline SSOP56 (SOT371-1)

3. Soldering

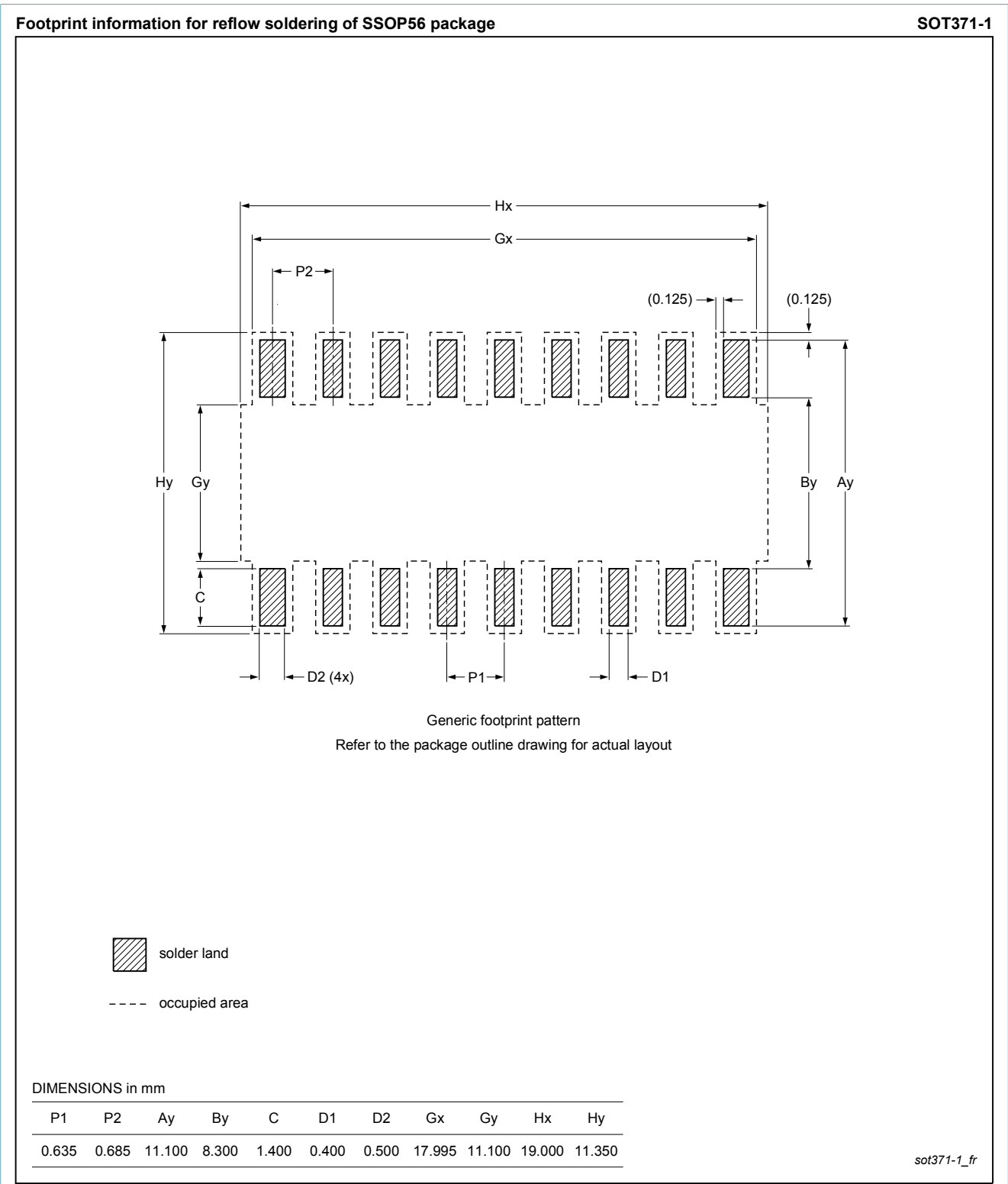


Fig. 2. Reflow soldering footprint for SSOP56 (SOT371-1)

4. Legal information

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Date of release: 8 February 2016